

INTEGRATED CIRCUITS

Population Comparison



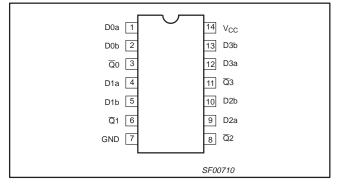


## 74F132

#### DESCRIPTION

The 74F132 contains four 2-input NAND gates which accept standard TTL input signals and provide standard TTL output levels. They are capable of transforming slowly changing input signals into sharply defined, jitter-free output signals. In addition, they have greater noise margin than conventional NAND gates. Each circuit contains a 2-input Schmitt trigger followed by a Darlington level shifter and a phase splitter driving a TTL totem-pole output. The Scmitt trigger uses positive feedback to effectively speed-up slow input transitions and provide different input threshold voltages for positive-going and negative-going input threshold (typically 800mV) is determined by resistor ratios and is essentially insensitive to temperature and supply voltage variations. As long as three inputs remain at a more positive voltage than  $V_{T+MAX}$ , the gate will respond in the transition of the other input as shown in Waveform 1.

## PIN CONFIGURATION



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)		
74F132	6.3ns	13mA		

## **ORDERING INFORMATION**

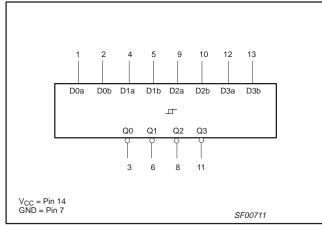
DESCRIPTION	$\begin{array}{l} \text{COMMERCIAL RANGE} \\ \text{V}_{\text{CC}} = 5\text{V} \pm 10\%, \\ \text{T}_{\text{amb}} = 0^{\circ}\text{C to} + 70^{\circ}\text{C} \end{array}$	PKG DWG #
14-pin plastic DIP	N74F132N	SOT27-1
14-pin plastic SO	N74F132D	SOT108-1

## INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

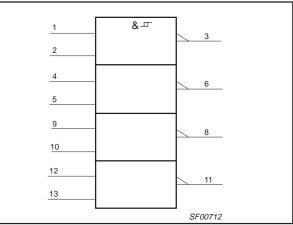
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW	
Dna, Dnb	Data inputs	1.0/1.0	20µA/0.6mA	
Qn	Data output	50/33	1.0mA/20mA	

NOTE: One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

## LOGIC SYMBOL

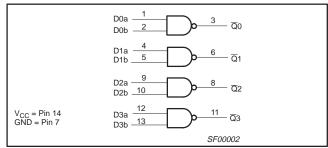


## **IEC/IEEE SYMBOL**



## 74F132

## LOGIC DIAGRAM



## **FUNCTION TABLE**

INP	UTS	OUTPUT
Dna	Dnb	Qn
L	L	Н
L	Н	Н
н	L	н
Н	Н	L

NOTES:

H = High voltage level L = Low voltage level

## **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	–0.5 to $V_{CC}$	V
I <sub>OUT</sub>	Current applied to output in Low output state	40	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature	-65 to +150	°C

## **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER		UNIT		
STWBOL	PARAMETER	MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

## 74F132

#### **DC ELECTRICAL CHARACTERISTICS**

(Over recommended operating free-air temperature range unless otherwise noted.)

CVMDO	PARAMETER							
SYMBOL			TEST CONDITIC	MIN	TYP <sup>2</sup>	MAX	UNIT	
V <sub>T+</sub>	Positive-going threshold		$V_{CC} = 5.0V$		1.5	1.7	2.0	V
V <sub>T-</sub>	Negative-going threshold-		$V_{CC} = 5.0V$		0.7	0.9	1.1	V
$\Delta V_{T}$	Hysteresis (V <sub>T+</sub> – V <sub>T</sub> )		$V_{CC} = 5.0V$		0.4	0.8		V
M			$V_{CC} = MIN,$	±10%V <sub>CC</sub>	2.5			
V <sub>OH</sub>	High-level output voltage		$V_{I=}V_{T-MAX}$ , $I_{OH} = MAX$	±5%V <sub>CC</sub>	2.7	3.4		V
V	OL Low-level output voltage		$V_{CC} = MIN,$	±10%V <sub>CC</sub>		0.30	0.50	V
VOL			$V_{I=}V_{T+MAX}$ , $I_{OL} = MAX$	±5%V <sub>CC</sub>		0.30	0.50	v
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$			-0.73	-1.2	V
I <sub>T+</sub>	Input current at positive-going thres	hold	$V_{CC} = 5.0V, V_{I} = V_{T+}$			0		μA
I <sub>T-</sub>	Input current at negative-going three	shold	$V_{CC} = 5.0V, V_{I} = V_{T-}$			-350		μA
lı	Input current at maximum input volta	age	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I <sub>IH</sub>	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μA
IIL	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>		$V_{CC} = MAX$		-60		-150	mA
1	Supply ourrest (total)	I <sub>CCH</sub>		V <sub>I N</sub> = GND		8.5	12.0	~^^
Icc	Supply current (total)	I <sub>CCL</sub>	V <sub>CC</sub> = MAX	V <sub>IN</sub> = 4.5V		13.0	19.5	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

 Por conditions shown as known as known as why or known, use the appropriate value specified under recommended operating conditions for the appricable type.
All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

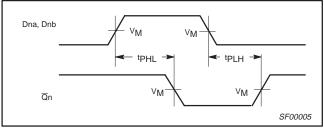
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## **AC ELECTRICAL CHARACTERISTICS**

					LIM	ITS		
SYMBOL	PARAMETER	TEST CONDITION	Τ <sub>έ</sub>	′ <sub>CC</sub> = +5.0′ <sub>amb</sub> = +25° 50pF, R <sub>L</sub> =	c	T <sub>amb</sub> = 0°C	0V $\pm$ 10% C to +70°C R <sub>L</sub> = 500 $\Omega$	UNIT
			MIN	ТҮР	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Dna, Dnb to $\overline{Q}n$	Waveform 1	3.5 4.5	5.5 6.0	7.0 8.5	3.0 4.5	8.5 9.0	ns

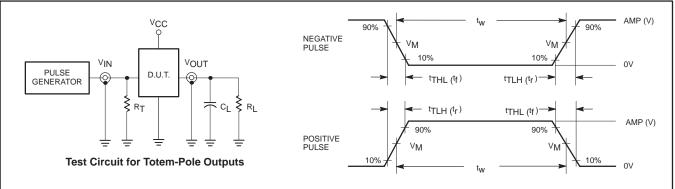
#### **AC WAVEFORMS**

For all waveforms,  $V_M = 1.5V$ .



Waveform 1. For Inverting Outputs

## **TEST CIRCUIT AND WAVEFORMS**



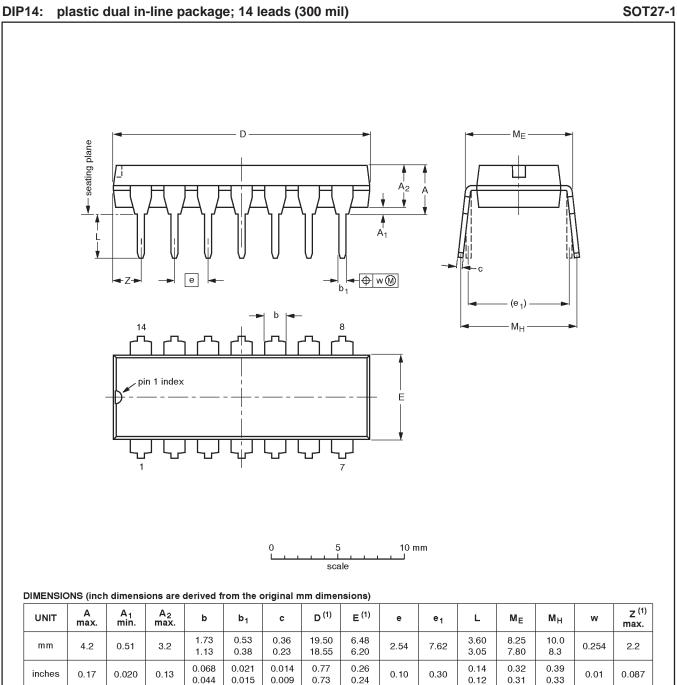
#### **DEFINITIONS:**

- R<sub>L</sub> = Load resistor;
- See AC ELECTRICAL CHARACTERISTICS for value. C<sub>L</sub> = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.

#### Input Pulse Definition

fomily	INP	UT PU	LSE REQU	REMEN	тѕ	
family	amplitude	V <sub>M</sub>	rep. rate	tw	t <sub>TLH</sub>	t <sub>THL</sub>
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

SF00006

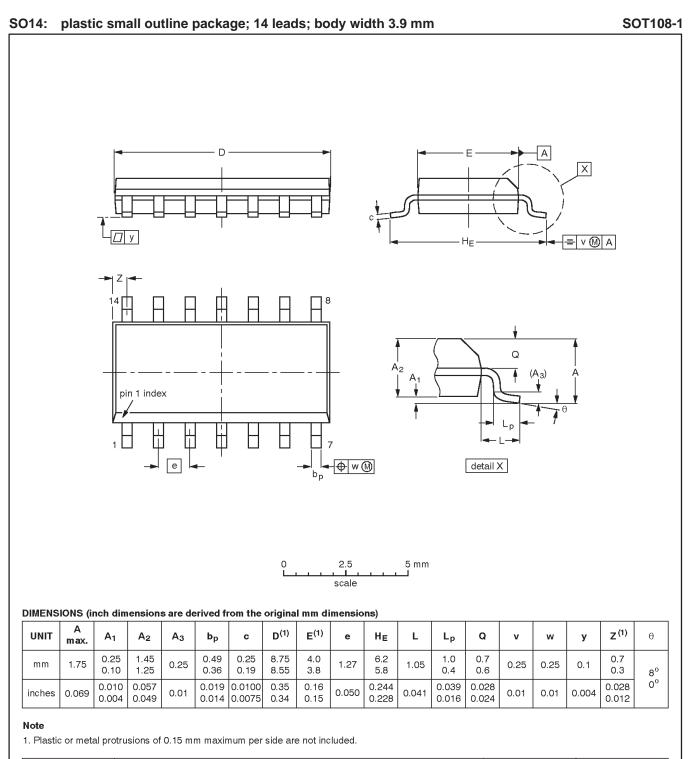


Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFERENCES					
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT27-1	050G04	MO-001AA				<del>-92-11-17</del> 95-03-11	

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OUTLINE		REFEF	RENCES	EUROPEAN		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT108-1	076E06S	MS-012AB				<del>-95-01-23</del> 97-05-22

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#### Data sheet status

Data sheet status	Product status	Definition <sup>[1]</sup>
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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